

# GSM30N15X

## 150V N-Channel MOSFETs

### Product Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

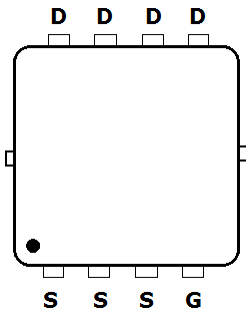
### Features

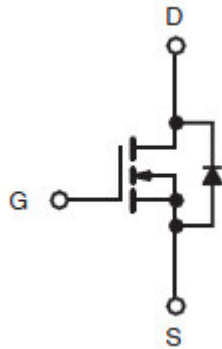
- 150V, 25A,  $R_{DS(ON)}=43m\Omega@V_{GS}=10V$
- 100% EAS Tested
- Green Device Available
- DFN5X6-8L package design

### Applications

- Motor Drive
- Power Tools
- LED Lighting
- Power Management in TV Converter
- DC/DC Converter

### Packages & Pin Assignments

GSM30N15XF (DFN5X6-8L)	
 <p>Top View</p>	
Pin	Description
1	Source
2	Source
3	Source
4	Gate
5	Drain
6	Drain
7	Drain
8	Drain



## Ordering Information

**GSM30N15 XF**
  
 Package Code ←

Part Number	Package	Quantity Reel
GSM30N15XF	DFN5X6-8L	3000 PCS

## Marking Information

Part Number
   
**30N15BHX**
  
**XWMMMM**
  
 GS Code

## Absolute Maximum Ratings

$T_A=25^{\circ}\text{C}$  Unless otherwise noted

Symbol	Parameter	Typical	Unit
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C=25^{\circ}\text{C}$	25
		$T_C=100^{\circ}\text{C}$	16
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	100	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	29	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	24	A
$P_D$	Power Dissipation ( $T_C=25^{\circ}\text{C}$ )	101	W
$T_J$	Operating Junction Temperature Range	-55 to +150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.23	$^{\circ}\text{C}/\text{W}$

## Electrical Characteristics

T<sub>A</sub>=25°C Unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	150			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.5	3.5	4.5	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =120V, V <sub>GS</sub> =0V			1	μA
		V <sub>DS</sub> =120V, V <sub>GS</sub> =0V, T <sub>J</sub> =85°C			10	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A		36	43	mΩ
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =3A		7		S
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current			25	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A			1	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =100V, I <sub>F</sub> =10A, dI/dt=100A/μs, T <sub>J</sub> =25°C		70		nS
Q <sub>rr</sub>	Reverse Recovery Charge			250		nC
<b>Dynamic</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =75V, V <sub>GS</sub> =10V, I <sub>D</sub> =15A		17.4		nC
Q <sub>gs</sub>	Gate-Source Charge			2.7		
Q <sub>gd</sub>	Gate-Drain Charge			6.1		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =75V, V <sub>GS</sub> =0V, f=1MHz		835		pF
C <sub>oss</sub>	Output Capacitance			75		
C <sub>rss</sub>	Reverse Transfer Capacitance			7		
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =75V, I <sub>D</sub> =15A, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω		4.6		ns
t <sub>r</sub>				15		
t <sub>d(off)</sub>	Turn-Off Time			27		
t <sub>f</sub>				8		

## Typical Performance Characteristics

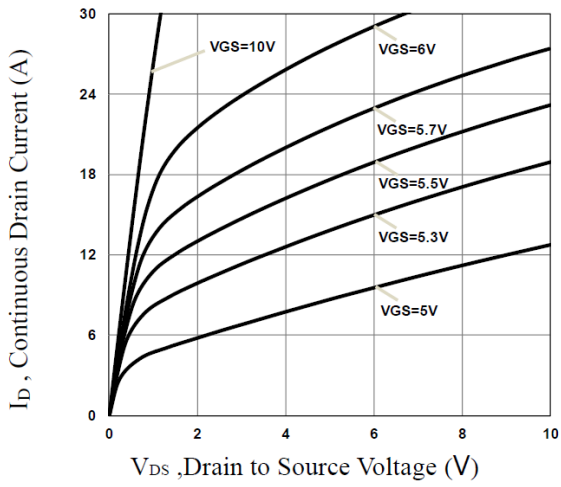


Figure 1. Output Characteristics

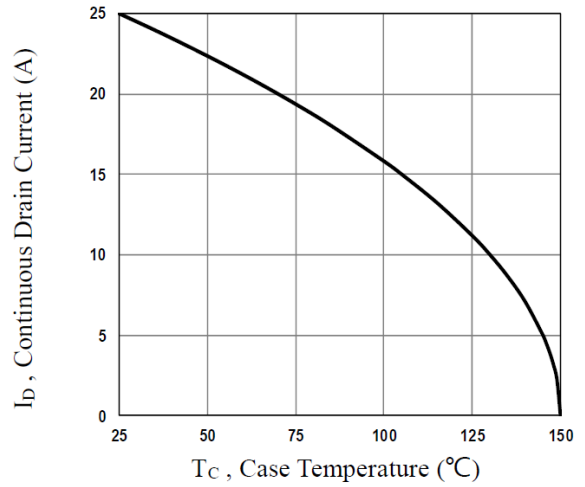


Figure 2. Continuous Drain Current vs.  $T_c$

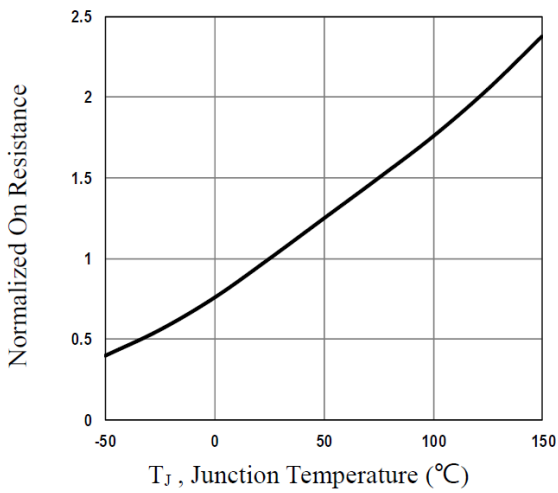


Figure 3. Normalized  $R_{DS(ON)}$  vs.  $T_J$

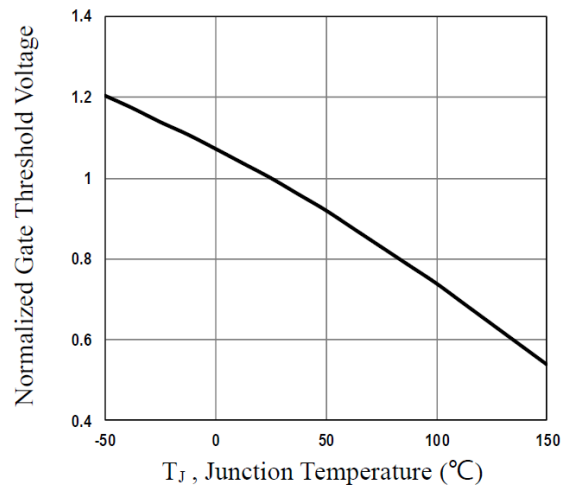


Figure 4. Normalized  $V_{th}$  vs.  $T_J$

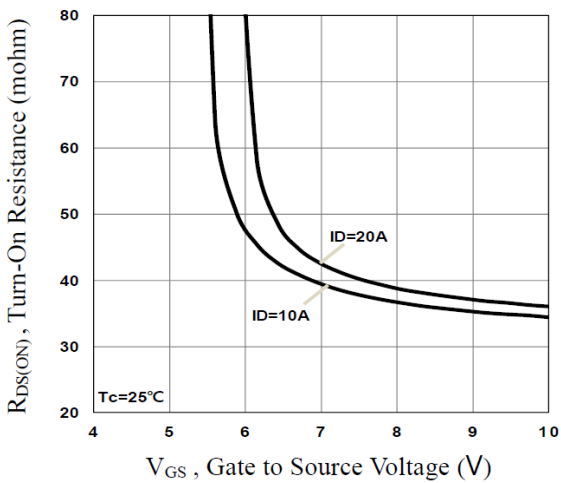


Figure 5. Turn-On Resistance vs.  $V_{GS}$

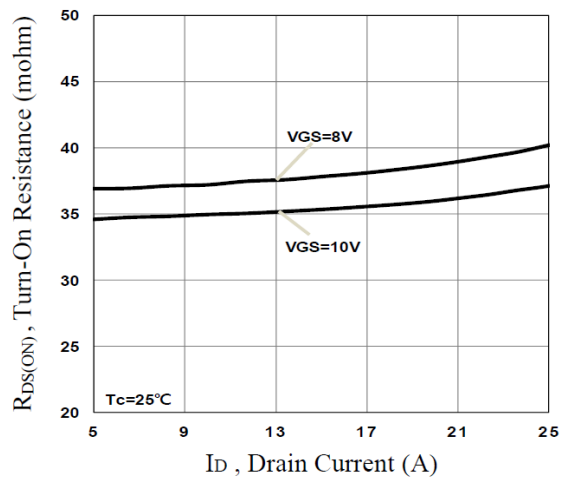


Figure 6. Turn-On Resistance vs.  $I_D$

## Typical Performance Characteristics (Continue)

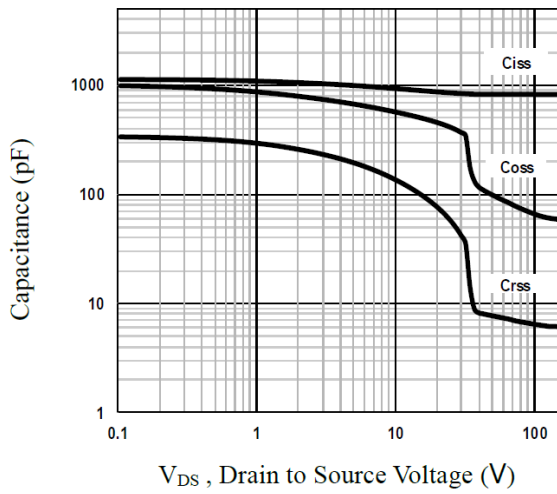


Figure 7. Capacitance

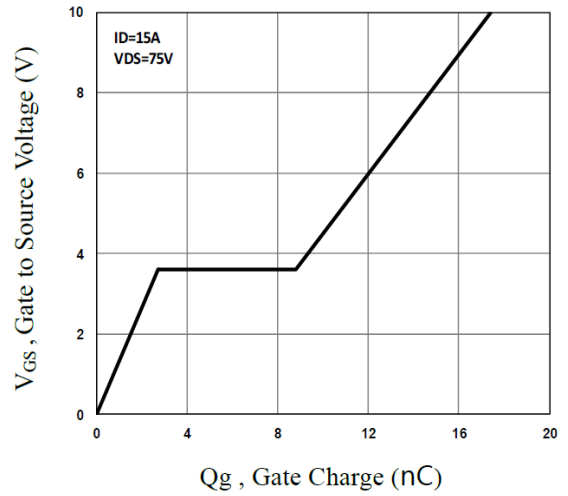


Fig 8. Gate Charge Characteristics

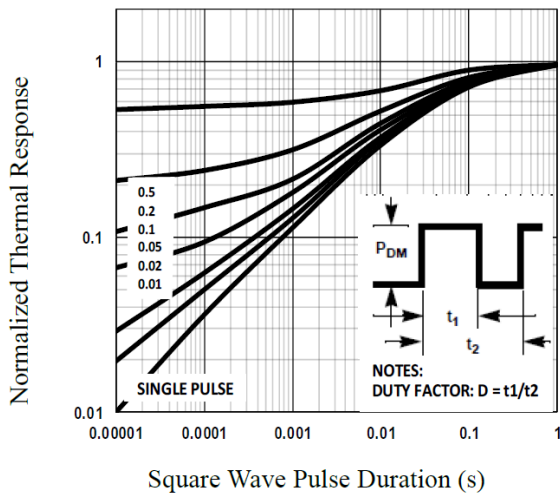


Fig.9 Normalized Transient Impedance

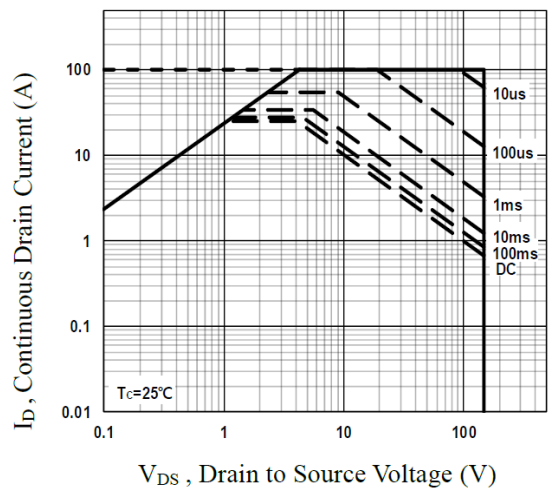


Figure 10. Maximum Safe Operating Area

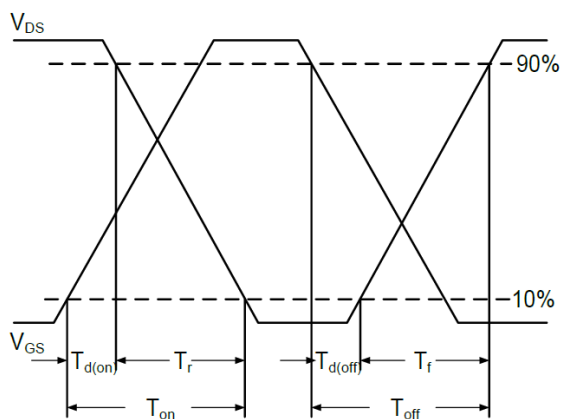


Fig 11. Switching Time Waveform

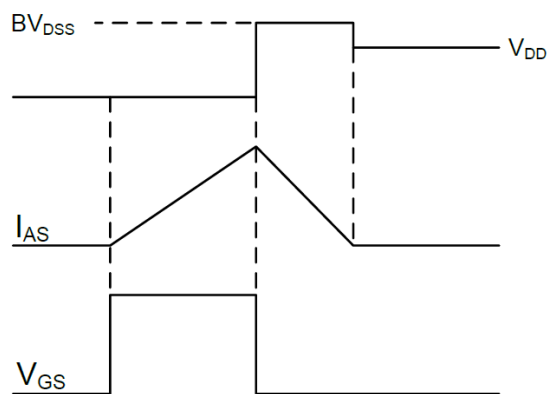
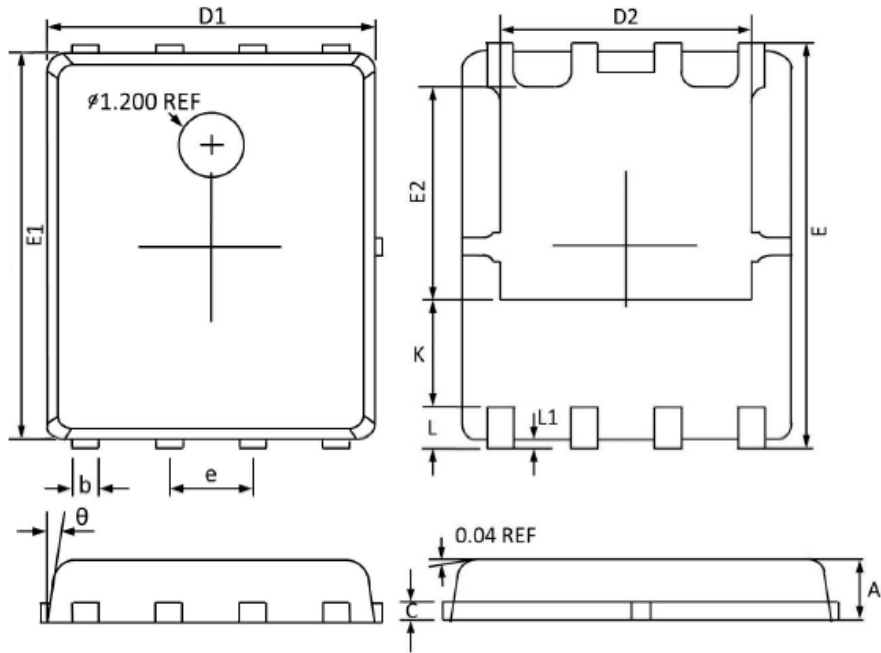


Fig 12. EAS Waveform

## Package Dimension

### DFN5X6-8L









Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.800	1.200	0.031	0.047
b	0.250	0.510	0.009	0.020
c	0.200	0.300	0.008	0.012
D1	4.800	5.400	0.189	0.212
D2	3.610	4.310	0.142	0.170
E	5.850	6.300	0.230	0.248
E1	5.450	5.960	0.215	0.235
E2	3.270	3.920	0.128	0.154
e	1.270 BSC		0.050 BSC	
H	0.380	0.650	0.015	0.026
K	1.400 REF		0.055 REF	
L	0.380	0.710	0.015	0.028
L1	0.050	0.250	0.002	0.009
θ	0°	12°	0°	12°

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## CONTACT US

GS Headquarter	
	4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd Neihu District Taipei City 114, Taiwan (R.O.C)
	886-2-2657-9980
	886-2-2657-3630
	sales_twn@gs-power.com

RD Division	
	824 Bolton Drive Milpitas. CA. 95035
	1-408-457-0587